



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

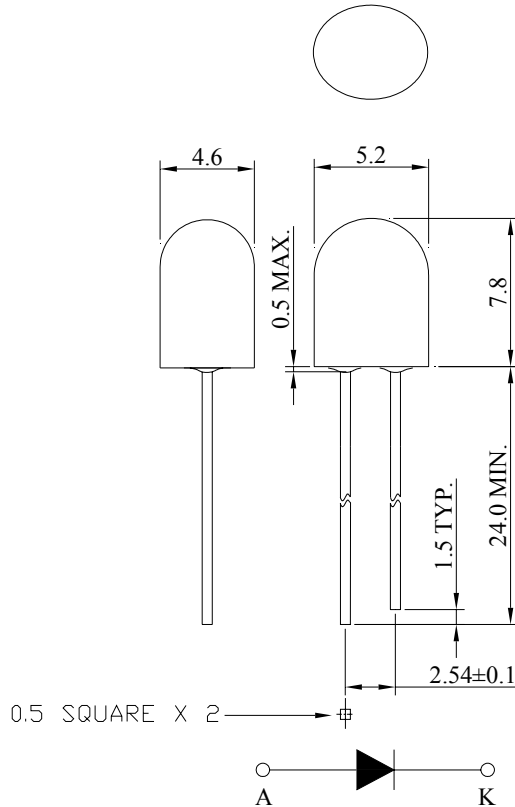
PART NO. : MT5470E-OR

5.2×4.6mm OVAL LED LAMP



Description

This amber lamp is made with AlGaInP/GaAs chip and white diffused epoxy resin.



Notes:

1. All dimensions are in mm.
2. Tolerance is ±0.25mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
MT5470E-OR	AlGaInP/GaAs	Amber	White diffused

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	125	mW
Reverse Voltage	V _R	5	V
D.C. Forward Current	I _f	50	mA
Reverse (Leakage) Current	I _r	100	μ A
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	200	mA
Operating Temperature Range	T _{opr.}	-40 to +95	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C
Soldering Temperature(1.6mm from body)	T _{sol.}	Dip Soldering : 260°C for 5 sec. Hand Soldering : 350°C for 3 sec.	

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =20mA	2130	3000		mcd
Forward Voltage	V _f	I _f =20mA		2.1	2.6	V
Peak Wavelength	λ _p	I _f =20mA		610		nm
Dominant Wavelength	λ _d	I _f =20mA	600	605	609	nm
Reverse (Leakage) Current	I _r	V _r =5V			100	μA
Viewing Angle	VERTICAL	2θ 1/2	I _f =20mA		40	deg
	HORIZONTAL	2θ 1/2	I _f =20mA		60	
Spectrum Line Halfwidth	Δλ	I _f =20mA		17		nm

Notes: 1. The datas tested by IS tester.

2. Customer's special requirements are also welcome.

Specifications for Bin Grading:

I_v(mcd)		
BIN	MIN.	MAX.
V	2130	3000
W	3000	4180
X	4180	5860

Specifications for Vf Group:

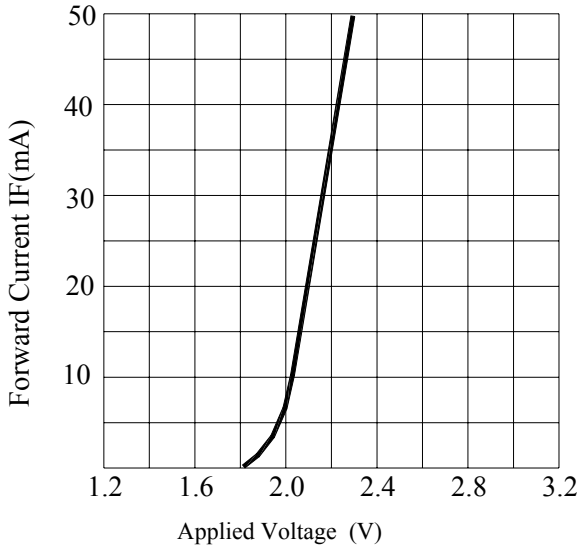
V_f(V)		
Group	MIN.	MAX.
V1	1.6	1.8
V2	1.8	2.0
V3	2.0	2.2
V4	2.2	2.4
V5	2.4	2.6

***Majority VF bins are highlighted in Yellow.**

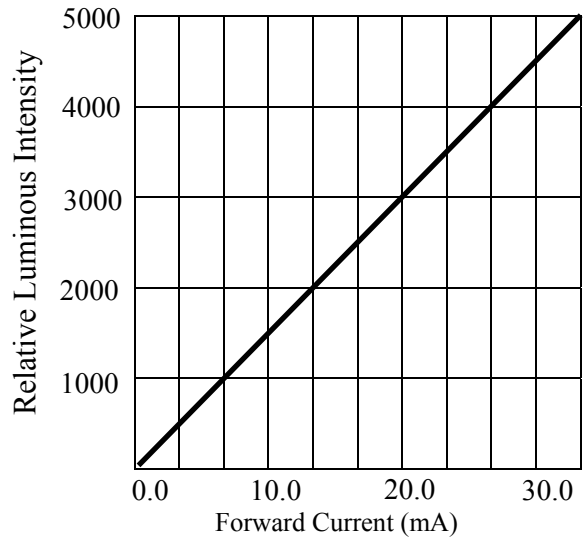
Specifications for Wavelength Group:

λ d(nm)		
Group	MIN.	MAX.
X2	600	603
X3	603	606
X4	606	609

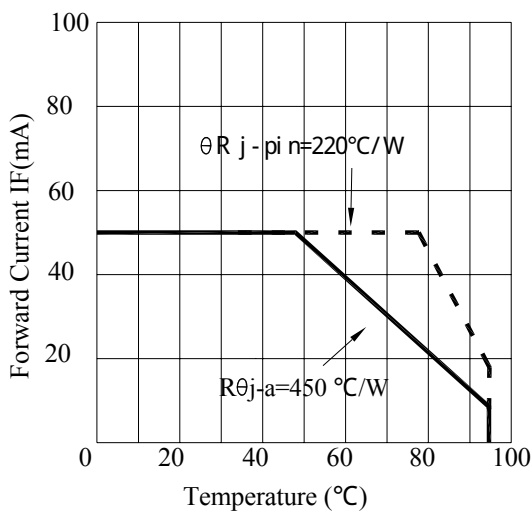
Typical Electrical / Optical Characteristics Curves :



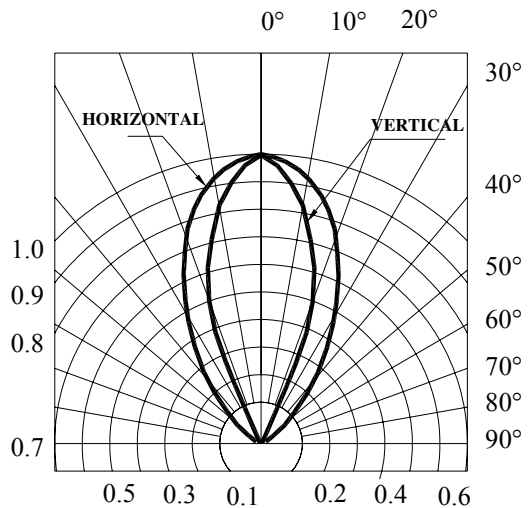
FORWARD CURRENT VS. APPLIED VOLTAGE



FORWARD CURRENT VS. LUMINOUS INTENSITY



FORWARD CURRENT VS. AMBIENT TEMPERATURE



RADIATION DIAGRAM

Precautions:

TAKE NOTE OF THE FOLLOWING IN USE OF LED

1. Temperature in use

Since the light generated inside the LED needs to be emitted to outside efficiently, a resin with high light transparency is used; therefore, additives to improve the heat resistance or moisture resistance (silica gel, etc) which are used for semiconductor products such as transistors cannot be added to the resin.

Consequently, the heat resistant ability of the resin used for LED is usually low; therefore, please be careful on the following during use.

Avoid applying external force, stress, and excessive vibration to the resins and terminals at high temperature. The glass transition temperature of epoxy resin used for the LED is approximately 120-130°C.

At a temperature exceeding this limit, the coefficient of linear expansion of the resin doubles or more compared to that at normal temperature and the resin is softened.

If external force or stress is applied at that time, it may cause a wire rupture.

2. Soldering

Please be careful on the following at soldering.

After soldering, avoid applying external force, stress, and excessive vibration until the products go to cooling process (normal temperature), <Same for products with terminal leads>

(1) Soldering measurements:

Distance between melted solder side to bottom of resin shall be 1.6mm or longer.

(2) Dip soldering :

Pre-heat: 90°C max. (Backside of PCB), Within 60 seconds.

Solder bath: 260±5°C (Solder temperature), Within 5 seconds.

(3) Hand soldering: 350°C max. (Temperature of soldering iron tip), Within 3 seconds.

3. Insertion

Pitch of the LED leads and pitch of mounting holes need to be same.

4. Others

Since the heat resistant ability of the LED resin is low, SMD components are used on the same PCB, please mount the LED after adhesive baking process for SMD components. In case adhesive baking is done after LED lamp insertion due to a production process reason, make sure not to apply external force, stress, and excessive vibration to the LED and follow the conditions below.

Baking temperature: 120°C max. Baking time: Within 60 seconds.

If soldering is done sequentially after the adhesive baking, please perform the soldering after cooling down the LED to normal temperature.